

Set forth below is a clean set of all amendments to the claims. The actual amendments to the claims are shown in the attachment.

In the Claims

Please cancel claim 16.

Please substitute amended claims 1, 5, 9, 10 and 15 for pending claims 1, 5, 9, 10 and 15 as follows:

1. (Twice Amended) A hinge for use in a micro-assembly employing electrical power supplied from an electrical power source, the hinge comprising:
a silicon-on-insulator wafer including a bottom substrate layer, a middle buried oxide layer and a single crystal silicon device layer;
a ribbon hinge structure formed in the device layer of the silicon-on-insulator wafer and having an upper outer surface, wherein the ribbon hinge structure is flexible and capable of movement out of the plane of the device layer; and
an electrical conductor material carried on at least a portion of the upper outer surface of the ribbon hinge structure.

5. (Twice Amended) The invention according to claim 1 wherein the ribbon structure has at least one of (i) an isolation region formed within the ribbon structure, and within which is deposited the electrical conductor material, or (ii) an area of insulation material which has been deposited and then patterned on the ribbon structure, wherein conductors can then be placed on top of the insulation material.

9. (Amended) The invention according to claim 6 wherein the micro-device includes an isolation region, formed within the micro-device, and in which the electrical conductor material is deposited.

10. (Twice Amended) The invention according to claim 6 further including an isolation region formed within the ribbon structure, and within which is deposited the electrical conductor material.

15. (Twice Amended) The invention according to claim 6 wherein the ribbon structure is configured with a mechanical integrity which permits application of a lifting out-of-plane mechanical torque to lift the micro-device from 0° which is in a horizontal plane, to 90° or more out of the horizontal plane.